SAMSUNG
ELECTRO-MECHANICS


- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N: CL05B562KO5NNNC
- Description : CAP, 5.6nF, 16V, $\pm 10 \%$, X7R, 0402
A. Samsung Part Number

| CL | 05 | B | 562 | K | O | $\underline{5}$ | $\underline{N}$ | $\underline{N}$ | $\underline{N}$ | C |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| (1) | (2) | (3) | (4) | (5) | (6) | (7) | (8) | (9) | (10) | (11) |


| (1) Series | Samsung Multi-layer Ceramic Capacitor |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| (2) Size | 0402 (inch code) | L: 1.00 | $\pm 0.05 \mathrm{~mm}$ | W: | $0.50 \pm 0.05 \mathrm{~mm}$ |
| (3) Dielectric | X7R | (8) | Inner electrode |  | Ni |
| (4) Capacitance | 5.6 nF |  | Termination |  | Cu |
| (5) Capacitance | $\pm 10$ \% |  | Plating |  | Sn 100\% (Pb Free) |
| tolerance |  | (9) | Product |  | Normal |
| (6) Rated Voltage | 16 V | (10) | Special |  | Reserved for future use |
| (7) Thickness | $0.50 \pm 0.05 \mathrm{~mm}$ | (11) | Packaging |  | Cardboard Type, 7" reel |

## B. Structure \& Dimension



| Samsung P/N | Dimension(mm) |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
|  | L | W | T | BW |
| CL05B562KO5NNNC | $1.00 \pm 0.05$ | $0.50 \pm 0.05$ | $0.50 \pm 0.05$ | $0.25 \pm 0.10$ |

C. Samsung Reliablility Test and Judgement Condition

|  | Judgement | Test condition |
| :---: | :---: | :---: |
| Capacitance | Within specified tolerance | $1 \mathrm{kHz} \pm 10 \% / 1.0 \pm 0.2 \mathrm{Vrms}$ |
| Tan $\mathbf{\delta}^{\text {(DF) }}$ | 0.035 max. | *A capacitor prior to measuring the capacitance is heat treated at $150^{\circ} \mathrm{C}+0 /-10^{\circ} \mathrm{C}$ for 1 hour and maintained in ambient air for $24 \pm 2$ hours. |
| Insulation <br> Resistance | 10,000 Mohm or $100 \mathrm{Mohm} \times \mu \mathrm{F}$ Whichever is smaller | Rated Voltage 60~120 sec. |
| Appearance | No abnormal exterior appearance | Microscope ( $\times 10$ ) |
| Withstanding Voltage | No dielectric breakdown or mechanical breakdown | $250 \%$ of the rated voltage |
| Temperature Characteristics | X7R <br> (From- $55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$, Capacitance change should be within $\pm 15 \%$ ) |  |
| Adhesive Strength of Termination | No peeling shall be occur on the terminal electrode | $500 \mathrm{~g} \cdot \mathrm{f}$, for $10 \pm 1 \mathrm{sec}$. |
| Bending Strength | Capacitance change: within $\pm 12.5 \%$ | Bending to the limit (1mm) with $1.0 \mathrm{~mm} / \mathrm{sec}$. |
| Solderability | More than $75 \%$ of terminal surface is to be soldered newly | SnAg3.0Cu0.5 solder $245 \pm 5^{\circ} \mathrm{C}, 3 \pm 0.3 \mathrm{sec}$. <br> (preheating : 80~120 ${ }^{\circ} \mathrm{C}$ for $10 \sim 30 \mathrm{sec}$.) |
| Resistance to Soldering Heat | Capacitance change: within $\pm 7.5 \%$ Tan $\delta$, IR : initial spec. | Solder pot : $270 \pm 5^{\circ} \mathrm{C}, 10 \pm 1 \mathrm{sec}$. |
| Vibration Test | Capacitance change: within $\pm 5 \%$ Tan $\delta$, IR : initial spec. | Amplitude : 1.5 mm From 10 Hz to 55 Hz (return : 1 min .) 2hours $\times 3$ direction ( $x, y, z$ ) |
| Moisture <br> Resistance | Capacitance change: within $\pm 12.5 \%$ <br> Tan $\delta: 0.05$ max <br> IR : $\quad 500 \mathrm{Mohm}$ or $25 \mathrm{Mohm} \times \mu \mathrm{F}$ <br> Whichever is smaller | With rated voltage $40 \pm 2^{\circ} \mathrm{C}, 90 \sim 95 \% \mathrm{RH}, 500+12 /-0 \mathrm{hrs}$ |
| High Temperature Resistance | Capacitance change: within $\pm 12.5 \%$ <br> Tan $\delta: 0.05$ max <br> IR: $1,000 \mathrm{Mohm}$ or $50 \mathrm{Mohm} \times \mu \mathrm{F}$ <br> Whichever is smaller | With 200\% of the rated voltage Max. operating temperature 1000+48/-Ohrs |
| Temperature Cycling | Capacitance change: within $\pm 7.5 \%$ Tan $\delta$, IR : initial spec. | 1 cycle condition <br> Min. operating temperature $\quad \rightarrow \quad 25^{\circ} \mathrm{C}$ <br> $\rightarrow$ Max. operating temperature $\rightarrow 25^{\circ} \mathrm{C}$ <br> 5 cycle test |

※ The reliability test condition can be replaced by the corresponding accelerated test condition.

## D. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : $260+0 /-5^{\circ} \mathrm{C}$, 10 sec . Max )

Product specifications included in the specifications are effective as of March 1, 2013.
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